Rochester Electronics

Datasheet

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
    - Class Q Military
    - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)

    - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

SN74LS259

8-Bit Addressable Latch

The SN74LS259 is a high-speed 8-Bit Addressable Latch designed for general purpose storage applications in digital systems. It is a multifunctional device capable of storing single line data in eight addressable latches, and also a 1-of-8 decoder and demultiplexer with active HIGH outputs. The device also incorporates an active LOW common Clear for resetting all latches, as well as, an active LOW Enable.

- Serial-to-Parallel Conversion
- Eight Bits of Storage With Output of Each Bit Available
- Random (Addressable) Data Entry
- Active High Demultiplexing or Decoding Capability
- Easily Expandable
- Common Clear

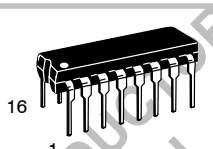
GUARANTEED OPERATING RANGES

Symbol	Parameter	Min	Typ	Max	Unit
V_{CC}	Supply Voltage	4.75	5.0	5.25	V
T_A	Operating Ambient Temperature Range	0	25	70	°C
I_{OH}	Output Current – High			–0.4	mA
I_{OL}	Output Current – Low			8.0	mA

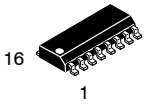
ON Semiconductor™

http://onsemi.com

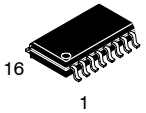
LOW POWER SCHOTTKY



PLASTIC
N SUFFIX
CASE 648



SOIC
D SUFFIX
CASE 751B



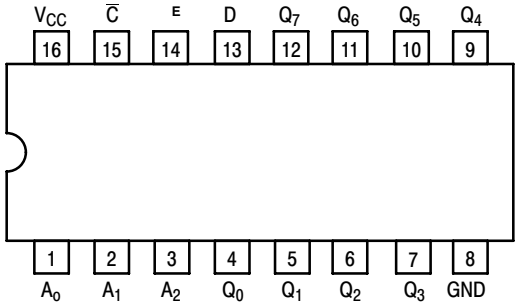
SOEIAJ
M SUFFIX
CASE 966

ORDERING INFORMATION

Device	Package	Shipping
SN74LS259N	16 Pin DIP	2000 Units/Box
SN74LS259D	SOIC–16	38 Units/Rail
SN74LS259DR2	SOIC–16	2500/Tape & Reel
SN74LS259M	SOEIAJ–16	See Note 1
SN74LS259MEL	SOEIAJ–16	See Note 1

1. For ordering information on the EIAJ version of the SOIC package, please contact your local ON Semiconductor representative.

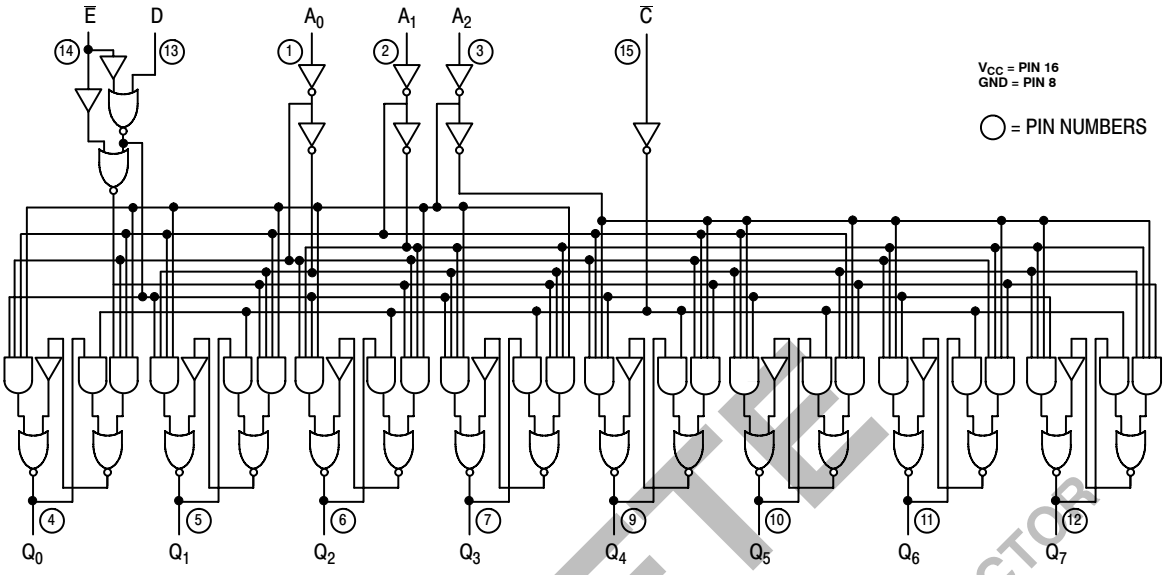
CONNECTION DIAGRAM DIP (TOP VIEW)



PIN NAMES		**LOADING** (Note a) HIGH	LOW
A_0, A_1, A_2	Address Inputs	0.5 U.L.	0.25 U.L.
D	Data Input	0.5 U.L.	0.25 U.L.
$\overline{E}$	Enable (Active LOW) Input	1.0 U.L.	0.5 U.L.
$\overline{C}$	Clear (Active LOW) Input	0.5 U.L.	0.25 U.L.
$Q_0 - Q_7$	Parallel Latch Outputs	10 U.L.	5 U.L.

NOTES:
a) 1 TTL Unit Load (U.L.) = 40 μA HIGH/1.6 mA LOW.

LOGIC DIAGRAM



FUNCTIONAL DESCRIPTION

The SN74LS259 has four modes of operation as shown in the mode selection table. In the addressable latch mode, data on the Data line (D) is written into the addressed latch.The addressed latch will follow the data input with all non-addressed latches remaining in their previous states. In the memory mode, all latches remain in their previous state and are unaffected by the Data or Address inputs.

In the one-of-eight decoding or demultiplexing mode, the addressed output will follow the state of the D input with all other inputs in the LOW state. In the clear mode all outputs are LOW and unaffected by the address and data inputs.

When operating the SN74LS259 as an addressable latch, changing more then one bit of the address could impose a transient wrong address. Therefore, this should only be done while in the memory mode.

The truth table below summarizes the operations.

MODE SELECTION

$\overline{E}$	$\overline{C}$	MODE
L	H	Addressable Latch
H	H	Memory
L	L	Active HIGH Eight-Channel Demultiplexer
H	L	Clear

TRUTH TABLE

						PRESENT OUTPUT STATES								
$\overline{C}$	$\overline{E}$	D	A_0	A_1	A_2	Q_0	Q_1	Q_2	Q_3	Q_4	Q_5	Q_6	Q_7	MODE
L	H	X	X	X	X	L	L	L	L	L	L	L	L	Clear
L	L	L	L	L	L	L	L	L	L	L	L	L	L	Demultiplex
L	L	H	L	L	L	H	L	L	L	L	L	L	L	
L	L	L	H	L	L	L	L	L	L	L	L	L	L	
L	L	H	H	L	L	L	H	L	L	L	L	L	L	
•	•	•		•					•					
•	•	•		•					•					
•	•	•		•					•					
•	•	•		•					•					
•	•	•		•					•					
L	L	H	H	H	H	L	L	L	L	L	L	L	H	
H	H	X	X	X	X	Q_{N-1} →								Memory
H	I	I	L	L	L	L	Q_{N-1}	Q_{N-1}	Q_{N-1} →					Addressable
H	L	H	L	L	L	H	Q_{N-1}	Q_{N-1} →						Latch
H	L	L	H	L	L	Q_{N-1}	L	Q_{N-1} →						
H	L	H	H	L	L	Q_{N-1}	H	Q_{N-1} →						
•	•	•		•					•					
•	•	•		•					•					
•	•	•		•					•					
•	•	•		•					•					
•	•	•		•					•					
H	L	L	H	H	H	Q_{N-1} →						Q_{N-1}	L	
H	L	H	H	H	H	Q_{N-1} →						Q_{N-1}	H	

X = Don't Care Condition
L = LOW Voltage Level
H = HIGH Voltage Level
Q_{N-1} = Previous Output State

DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

Symbol	Parameter	Limits			Unit	Test Conditions	
		Min	Typ	Max			
V_{IH}	Input HIGH Voltage	2.0			V	Guaranteed Input HIGH Voltage for All Inputs	
V_{IL}	Input LOW Voltage			0.8	V	Guaranteed Input LOW Voltage for All Inputs	
V_{IK}	Input Clamp Diode Voltage		−0.65	−1.5	V	V_{CC} = MIN, I_{IN} = −18 mA	
V_{OH}	Output HIGH Voltage	2.7	3.5		V	V_{CC} = MIN, I_{OH} = MAX, V_{IN} = V_{IH} or V_{IL} per Truth Table	
V_{OL}	Output LOW Voltage		0.25	0.4	V	I_{OL} = 4.0 mA	V_{CC} = V_{CC} MIN, V_{IN} = V_{IL} or V_{IH} per Truth Table
			0.35	0.5	V	I_{OL} = 8.0 mA	
I_{IH}	Input HIGH Current			20	μA	V_{CC} = MAX, V_{IN} = 2.7 V	
				0.1	mA	V_{CC} = MAX, V_{IN} = 7.0 V	
I_{IL}	Input LOW Current			−0.4	mA	V_{CC} = MAX, V_{IN} = 0.4 V	
I_{OS}	Short Circuit Current (Note 2)	−20		−100	mA	V_{CC} = MAX	
I_{CC}	Power Supply Current			36	mA	V_{CC} = MAX	

2. Not more than one output should be shorted at a time, nor for more than 1 second.

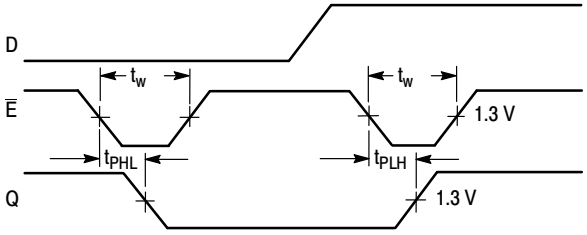
AC CHARACTERISTICS (T_A = 25°C, V_{CC} = 5.0 V)

Symbol	Parameter	Limits			Unit	Test Conditions
		Min	Typ	Max		
t_{PLH} t_{PHL}	Turn-Off Delay, Enable to Output Turn-On Delay, Enable to Output		22 15	35 24	ns ns	C_L = 15 pF
t_{PLH} t_{PHL}	Turn-Off Delay, Data to Output Turn-On Delay, Data to Output		20 13	32 21	ns ns	
t_{PLH} t_{PHL}	Turn-Off Delay, Address to Output Turn-On Delay, Address to Output		24 18	38 29	ns ns	
t_{PHL}	Turn-On Delay, Clear to Output		17	27	ns	

AC SET-UP REQUIREMENTS (T_A = 25°C, V_{CC} = 5.0 V)

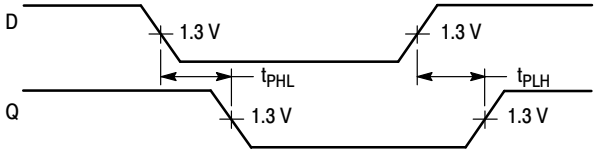
Symbol	Parameter	Limits			Unit
		Min	Typ	Max	
t_s	Input Setup Time	20			ns
t_W	Pulse Width, Clear or Enable	15			ns
t_h	Hold Time, Data	5.0			ns
t_h	Hold Time, Address	20			ns

AC WAVEFORMS



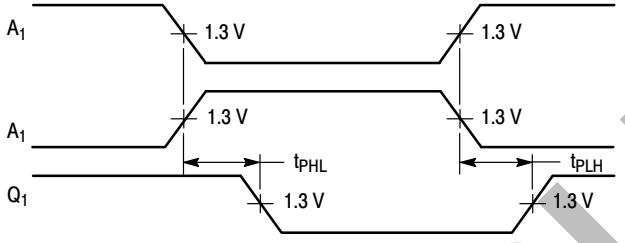
OTHER CONDITIONS: $\overline{C}$ = H, A = STABLE

Figure 1. Turn-on and Turn-off Delays, Enable To Output and Enable Pulse Width



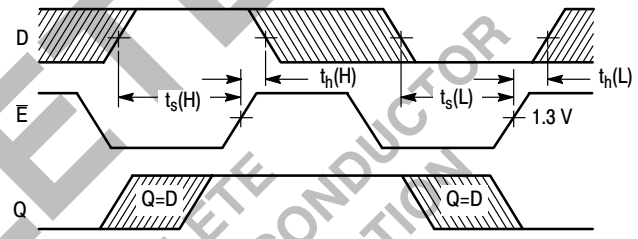
OTHER CONDITIONS: $\overline{E}$ = L, $\overline{C}$ = H, A = STABLE

Figure 2. Turn-on and Turn-off Delays, Data to Output



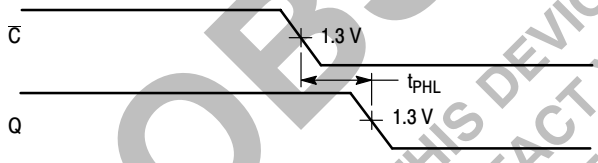
OTHER CONDITIONS: $\overline{E}$ = L, $\overline{C}$ = L, D = H

Figure 3. Turn-on and Turn-off Delays, Address to Output



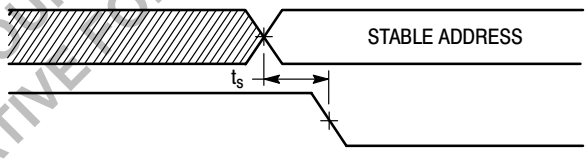
OTHER CONDITIONS: $\overline{C}$ = H, A = STABLE

Figure 4. Setup and Hold Time, Data to Enable



OTHER CONDITIONS: $\overline{E}$ = H

Figure 5. Turn-on Delay, Clear to Output



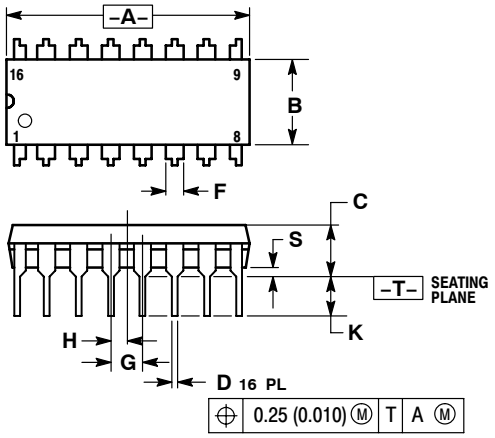
OTHER CONDITIONS: $\overline{C}$ = H

Figure 6. Setup Time, Address to Enable (See Notes 1 and 2)

NOTES:
1. The Address to Enable Setup Time is the time before the HIGH-to-LOW Enable transition that the Address must be stable so that the correct latch is addressed and the other latches are not affected.
2. The shaded areas indicate when the inputs are permitted to change for predictable output performance.

PACKAGE DIMENSIONS

N SUFFIX
PLASTIC PACKAGE
CASE 648−08
ISSUE R

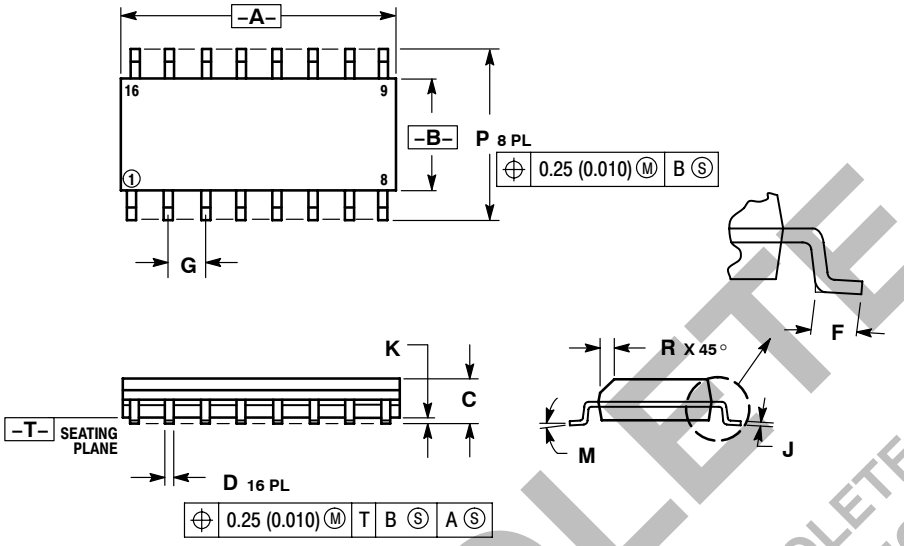


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

PACKAGE DIMENSIONS

D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751B–05
ISSUE J

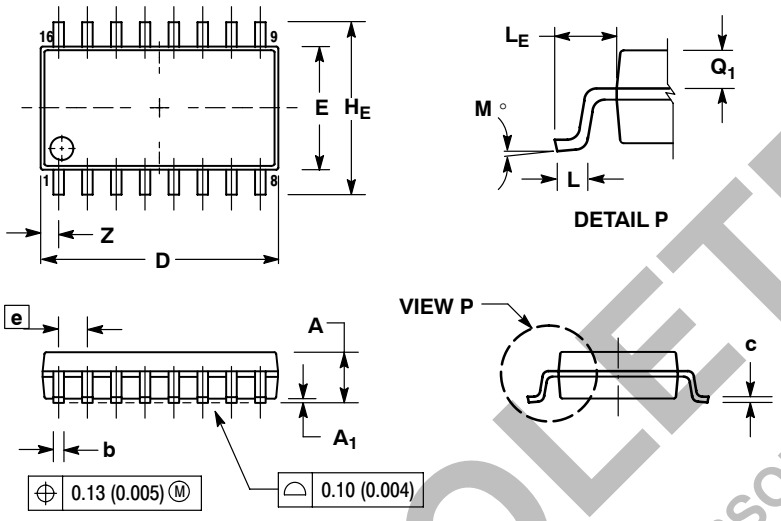


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

PACKAGE DIMENSIONS

M SUFFIX
SOEIAJ PACKAGE
CASE 966–01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

PUBLICATION ORDERING INFORMATION

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